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January 2015

## FDMC86160ET100

# N-Channel Shielded Gate PowerTrench<sup>®</sup> MOSFET 100 V, 43 A, 14 m $\Omega$

#### **Features**

- Extended T<sub>.1</sub> rating to 175°C
- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)}$  = 14 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 9 A
- Max  $r_{DS(on)} = 23 \text{ m}\Omega$  at  $V_{GS} = 6 \text{ V}$ ,  $I_D = 7 \text{ A}$
- High performance technology for extremely low r<sub>DS(on)</sub>
- Termination is Lead-free and RoHS Compliant

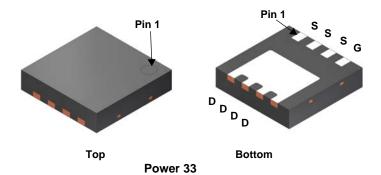


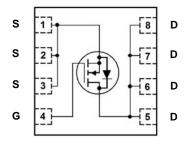
### **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance. This device is well suited for applications where ulta low  $R_{DS\ (on)}$  is required in small spaces such as High performance VRM, POL and orring functions

## **Applications**

- Bridge Topologies
- Synchronous Rectifier





## MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol		Parameter				Units
V <sub>DS</sub>	Drain to Source \	/oltage			100	V
V <sub>GS</sub>	Gate to Source V	/oltage			±20	V
	Drain Current	-Continuous	T <sub>C</sub> = 25 °C	(Note 5)	43	
		-Continuous	T <sub>C</sub> = 100 °C	(Note 5)	31	^
'D		-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	9	Α
		-Pulsed		(Note 4)	204	
E <sub>AS</sub>	Single Pulse Ava	lanche Energy		(Note 3)	181	mJ
P <sub>D</sub>	Power Dissipatio	n	T <sub>C</sub> = 25 °C		65	W
	Power Dissipatio	n	T <sub>A</sub> = 25 °C	(Note 1a)	2.8	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and St	Operating and Storage Junction Temperature Range			-55 to +175	°C

## **Thermal Characteristics**

$R_{ heta JC}$	Thermal Resistance, Junction to Case	(Note 1)	2.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	53	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC86160ET	FDMC86160ET100	Power33	13 "	12 mm	3000 units

## Electrical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	octeristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		73		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V			1	μΑ
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	2.9	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-9		mV/°C
r <sub>DS(on)</sub> Static Drain to Source On Resistance		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9 A		11.2	14	
	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 7 \text{ A}$		16	23	$m\Omega$
	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9 A, T <sub>J</sub> = 125 °C		21	26		
9 <sub>FS</sub>	Forward Transconductance	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 9 A		43		S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 50.V V 0.V		968	1290	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$		241	320	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 – 1 1011 12		11	20	pF
$R_{\alpha}$	Gate Resistance		0.1	0.6	2.5	Ω

## **Switching Characteristics**

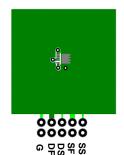
t <sub>d(on)</sub>	Turn-On Delay Time			9.7	19	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 50 \text{ V}, I_{D} = 9 \text{ A}$	Α,	3.6	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10 V, R <sub>GEN</sub> :	= 6 Ω	16	30	ns
t <sub>f</sub>	Fall Time			3.4	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V		15	22	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 V to 6 V$	$V_{DD} = 50 \text{ V},$	9.8	15	nC
$Q_{gs}$	Total Gate Charge		I <sub>D</sub> = 9 A	4.4		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			3.5		nC

## **Drain-Source Diode Characteristics**

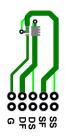
V	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 9 \text{ A}$	(Note 2)	0.79	1.3	V
v SD	Source to Drain Diode Forward voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.9 \text{ A}$	(Note 2)	0.72	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I = 0 A di/dt = 100 A/vo		47	75	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = 9 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		45	73	nC

Notes:

<sup>1.</sup> R<sub>0JA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0CA</sub> is determined by the user's board design.



53 °C/W when mounted on a a.1 in² pad of 2 oz copper



125 °C/W when mounted on b.a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300  $\mu\text{s},$  Duty cycle < 2.0%.
- 3.  $E_{AS}$  of 181 mJ is based on starting  $T_J$  = 25 °C, L = 3 mH,  $I_{AS}$  = 11 A,  $V_{DD}$  = 100 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH,  $I_{AS}$  = 35 A.
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

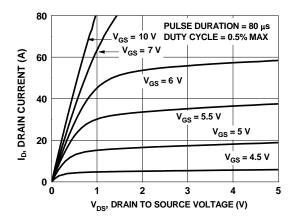


Figure 1. On-Region Characteristics

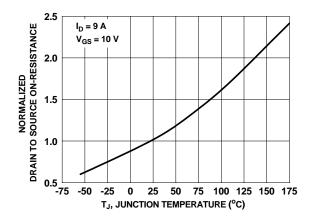


Figure 3. Normalized On-Resistance vs Junction Temperature

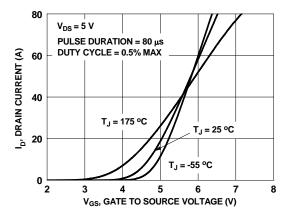


Figure 5. Transfer Characteristics

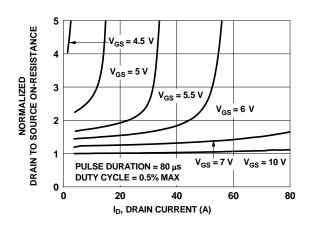


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

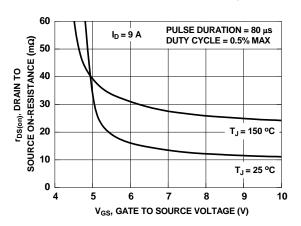


Figure 4. On-Resistance vs Gate to Source Voltage

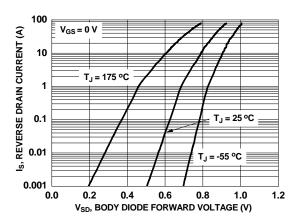


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

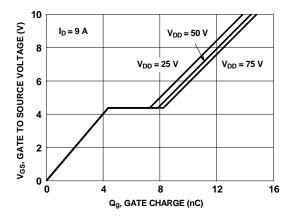


Figure 7. Gate Charge Characteristics

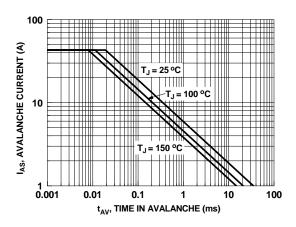


Figure 9. Unclamped Inductive Switching Capability

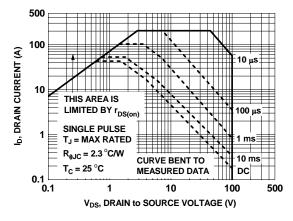


Figure 11. Forward Bias Safe Operating Area

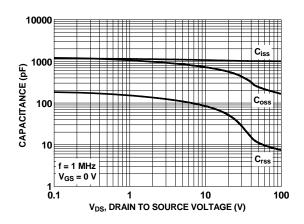


Figure 8. Capacitance vs Drain to Source Voltage

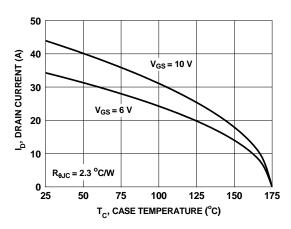


Figure 10. Maximum Continuous Drain Current vs Case Temperature

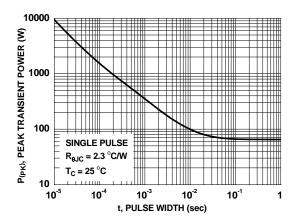


Figure 12. Single Pulse Maximum Power Dissipation



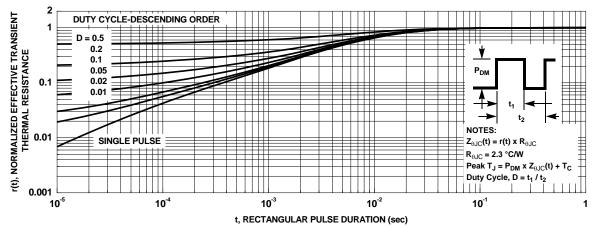
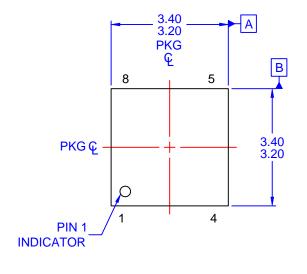
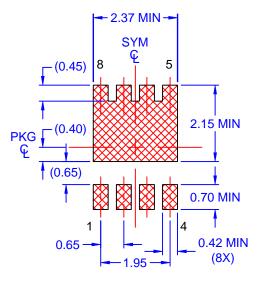
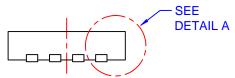


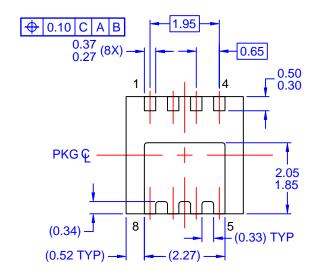
Figure 13. Junction-to-Case Transient Thermal Response Curve





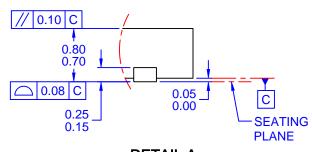


LAND PATTERN RECOMMENDATION



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- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
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